



Technical Bulletin

CuFlon Electroplating Ni/Au

Nickel-gold can be electrolytically pattern plated onto CuFlon using standard processes. We do not recommend gold plating post etch since delamination may occur – especially on thin traces. During the plating process hydrogen gas is released at the cathode. It is believed that the hydrogen gas undermines the metal to PTFE bond.

The below guidelines are provided to help minimize potential delamination. It is recommended that test panels are run to confirm compatibility of bath for plating onto CuFlon. If delamination issues are found, rebalance bath or consider an alternative finish.

Recommendations:

1. Solution should be as efficient as possible
2. Bath solution should be as low a pH as process allows
3. Plating time should be as short a duration as possible
4. Any surface preparation used prior to plating should be noncaustic and low pH (or neutral).

The following company has successfully gold plated onto our CuFlon material:

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